

# MICROFILL™ EVF

## Copper Via Fill

### *High-Performance Microvia Filling*

#### Description

MICROFILL™ EVF Via Fill provides enhanced via filling, with simultaneous through-hole plating, at surface thicknesses previously unattainable.

Formulated to operate in existing equipment over a broad range of operating conditions, MICROFILL™ EVF Copper Via Fill is suitable for both HDI and IC Substrate applications. Production proven to reduce plating thickness by 20%.

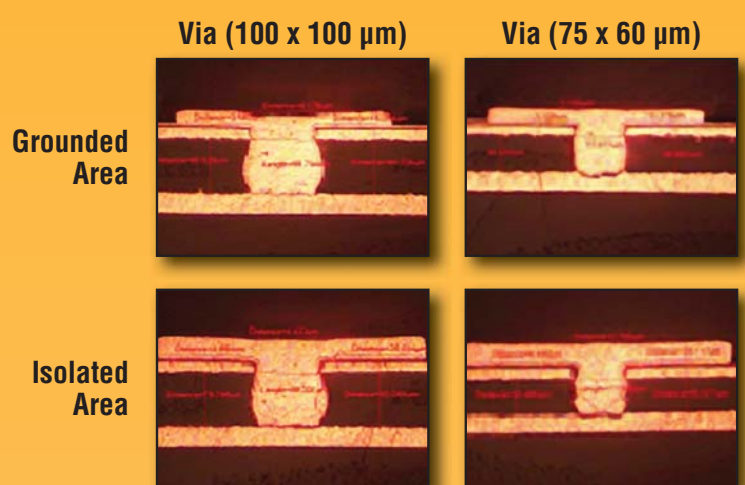
#### Benefits

- Low plating thickness (20  $\mu\text{m}$ )
- Exceptional microvia filling performances
- Simultaneous microvia filling and through-hole plating
- Compatibility with both panel and pattern plating processing
- Compatibility with both soluble and insoluble anodes
- Easily analyzed and controlled by conventional CVS
- Rectangle trace profile for wire bonding applications
- Excellent reliability



Through hole throwing power >80% (for 5:1 AR through hole at 1.8 ASD and 20  $\mu\text{m}$  copper thickness)

#### Pattern Filling Performance



Current Density: 18 ASF  
Flow Rate: 0.6 bar  
Copper Plated: 20  $\mu\text{m}$   
Plating Distribution:  $\pm 4 \mu\text{m}$   
Dimple: <10  $\mu\text{m}$

#### Trace Profile

